

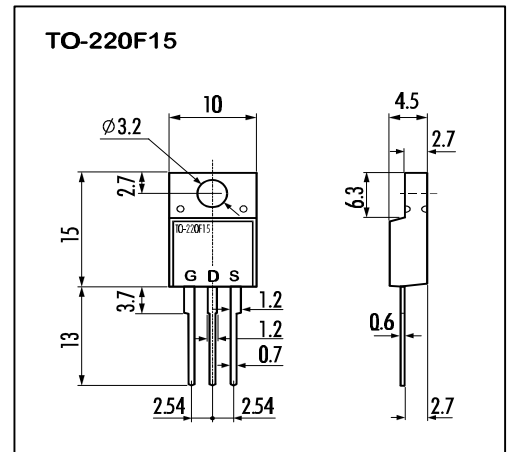
> **Features**

- High Current
- Low On-Resistance
- No Secondary Breakdown
- Low Driving Power
- Avalanche Rated

> **Applications**

- Motor Control
- General Purpose Power Amplifier
- DC-DC converters

> **Outline Drawing**

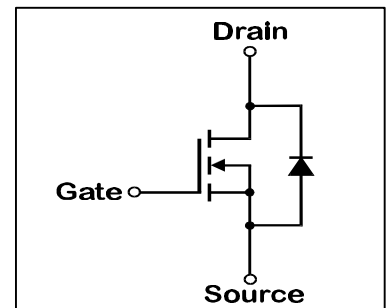


> **Maximum Ratings and Characteristics**

- Absolute Maximum Ratings (T<sub>C</sub>=25°C), unless otherwise specified

Item	Symbol	Rating	Unit
Drain-Source-Voltage	V <sub>DS</sub>	30	V
Continous Drain Current	I <sub>D</sub>	±50	A
Pulsed Drain Current	I <sub>D(puls)</sub>	±200	A
Gate-Source-Voltage	V <sub>GS</sub>	±16	V
Maximum Avalanche Energy	E <sub>AV</sub>	1441.5	mJ*
Max. Power Dissipation	P <sub>D</sub>	50	W
Operating and Storage Temperature Range	T <sub>ch</sub>	150	°C
	T <sub>stg</sub>	-55 ~ +150	°C

L=0.769mH, V<sub>CC</sub>=12V



- Electrical Characteristics (T<sub>C</sub>=25°C), unless otherwise specified

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown-Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =1mA V <sub>GS</sub> =0V	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	I <sub>D</sub> =1mA V <sub>DS</sub> =V <sub>GS</sub>	1,0	1,5	2,0	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V T <sub>ch</sub> =25°C		10	500	μA
		V <sub>GS</sub> =0V T <sub>ch</sub> =125°C		0,2	1,0	mA
Gate Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±16V V <sub>DS</sub> =0V		10	100	nA
Drain Source On-State Resistance	R <sub>DS(on)</sub>	I <sub>D</sub> =50A V <sub>GS</sub> =4V		8,0	10,5	mΩ
		I <sub>D</sub> =50A V <sub>GS</sub> =10V		5,3	6,8	mΩ
Forward Transconductance	g <sub>fs</sub>	I <sub>D</sub> =50A V <sub>DS</sub> =25V	35	70		S
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V		3900	5850	pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> =0V		2000	3000	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f=1MHz		850	1280	pF
Turn-On-Time t <sub>on</sub> (t <sub>on</sub> =t <sub>d(on)</sub> +t <sub>r</sub> )	t <sub>d(on)</sub>	V <sub>CC</sub> =15V		17	30	ns
	t <sub>r</sub>	V <sub>GS</sub> =10V		70	110	ns
	t <sub>d(off)</sub>	I <sub>D</sub> =100A		250	380	ns
Turn-Off-Time t <sub>off</sub> (t <sub>off</sub> =t <sub>d(off)</sub> +t <sub>f</sub> )	t <sub>f</sub>	R <sub>GS</sub> =10 Ω		180	270	ns
	I <sub>AV</sub>	L = 100μH T <sub>ch</sub> =25°C	50			A
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =50A V <sub>GS</sub> =0V T <sub>ch</sub> =25°C		1,0	1,5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =50A V <sub>GS</sub> =0V		65		ns
Reverse Recovery Charge	Q <sub>rr</sub>	-di/dt=100A/μs T <sub>ch</sub> =25°C		0,12		μC

- Thermal Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance	R <sub>th(ch-c)</sub>			2,5	°C/W
	R <sub>th(ch-a)</sub>			62,5	°C/W

N-channel MOS-FET			
30V	0,0105Ω	±50A	50W

# 2SK2890-01

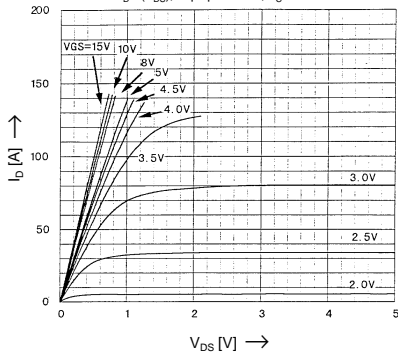
## FAP-IIIB Series



### > Characteristics

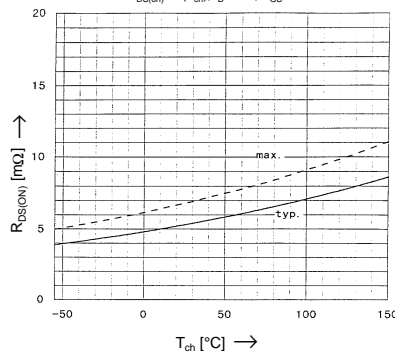
Typical Output Characteristics

$I_D = f(V_{DS})$ ; 80μs pulse test;  $T_C = 25^\circ\text{C}$



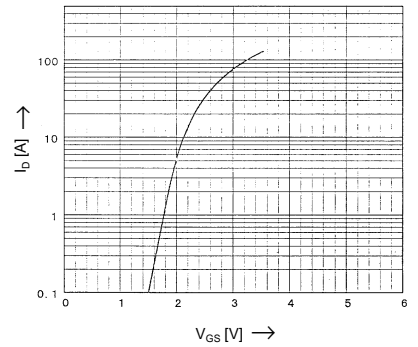
Drain-Source On-State Resistance vs.  $T_{ch}$

$R_{DS(on)} = f(T_{ch})$ ;  $I_D = 50A$ ;  $V_{GS} = 10V$



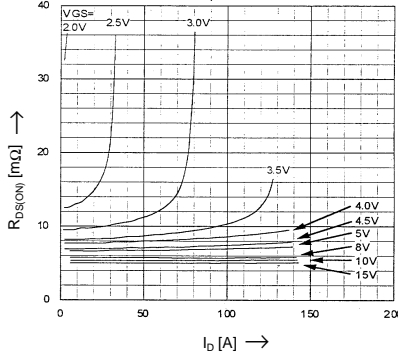
Typical Transfer Characteristics

$I_D = f(V_{GS})$ ; 80μs pulse test;  $V_{DS} = 25V$ ;  $T_C = 25^\circ\text{C}$



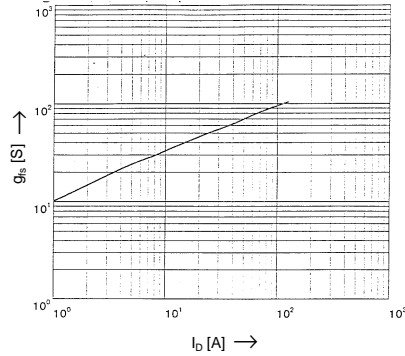
Typical Drain-Source On-State-Resistance vs.  $I_D$

$R_{DS(on)} = f(I_D)$ ; 80μs pulse test;  $T_C = 25^\circ\text{C}$



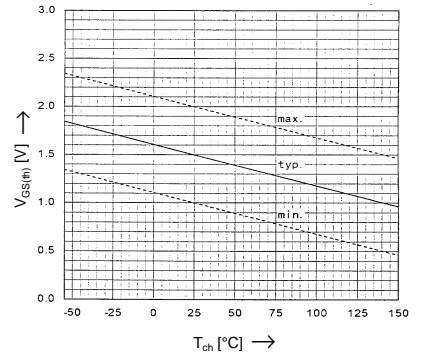
Typical Forward Transconductance vs.  $I_D$

$g_{fs} = f(I_D)$ ; 80μs pulse test;  $V_{DS} = 25V$ ;  $T_{ch} = 25^\circ\text{C}$



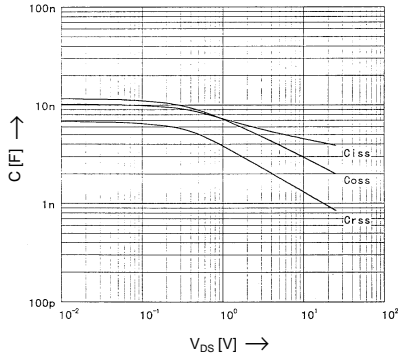
Gate Threshold Voltage vs.  $T_{ch}$

$V_{GS(th)} = f(T_{ch})$ ;  $I_D = 1mA$ ;  $V_{DS} = V_{GS}$



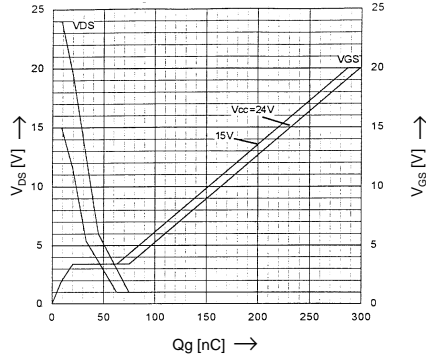
Typical Capacitances vs.  $V_{DS}$

$C = f(V_{DS})$ ;  $V_{GS} = 0V$ ;  $f = 1MHz$



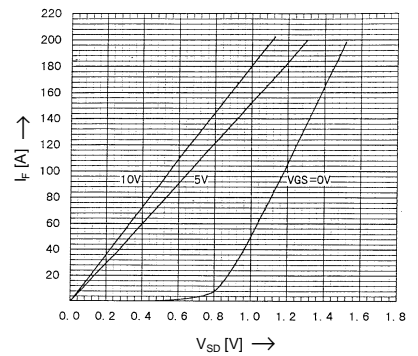
Typical Gate Charge Characteristic

$V_{GS} = f(Q_g)$ ;  $I_D = 100A$ ;  $T_C = 25^\circ\text{C}$



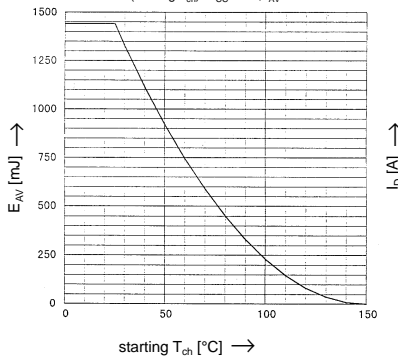
Forward Characteristics of Reverse Diode

$I_F = f(V_{SD})$ ; 80μs pulse test;  $T_{ch} = 25^\circ\text{C}$



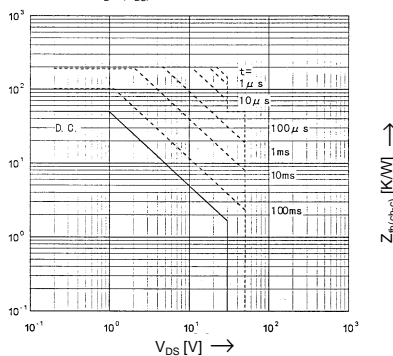
Maximum Avalanche Energy vs. starting  $T_{ch}$

$E_{AV} = f(\text{starting } T_{ch})$ ;  $V_{CC} = 12V$ ;  $I_{AV} \leq 50A$



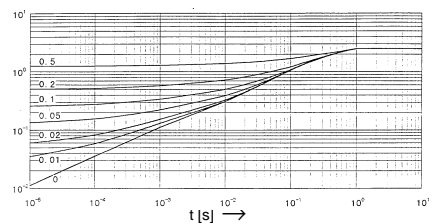
Safe Operation Area

$I_D = f(V_{DS})$ ;  $D = 0.01$ ;  $T_C = 25^\circ\text{C}$



Transient Thermal impedance

$Z_{th(ch-c)} = f(t)$  parameter:  $D = 1/T$



N-channel MOS-FET			
30V	0,0105Ω	±50A	50W

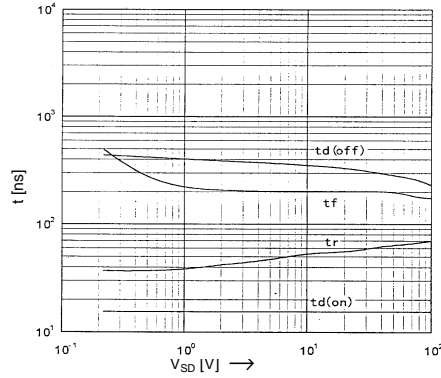
# 2SK2890-01

## FAP-IIIB Series

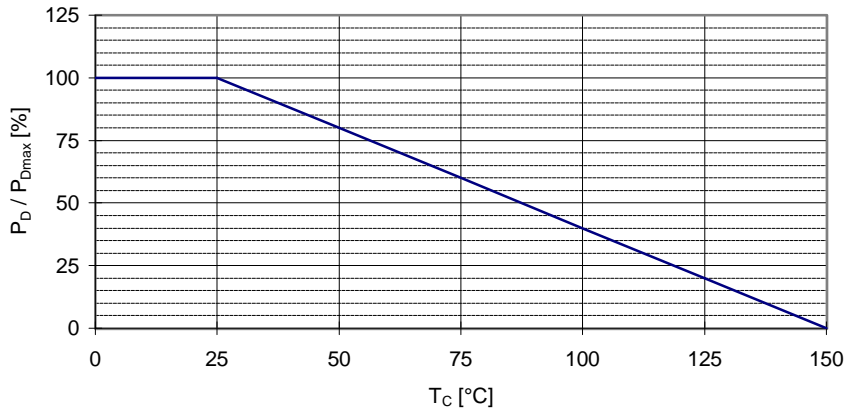


### > Characteristics

Typical Switching Characteristics  
 $t=f(I_D)$ :  $V_{CC} = 15V$ ,  $V_{GS} = 10V$ ,  $R_G = 10\Omega$



Power Dissipation  
 $P_D=f(T_C)$



Maximum Avalanche Current vs. starting  $T_{ch}$   
 $I_{AV}=f(\text{starting } T_{ch})$

